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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO	
10.053,256	01-18-2002	Zhigang Wang	G0186	1274	
75	90 05/21/2003				
WAGNER, MURABITO & HAO LLP			EXAMINER		
Two North Mar Third Floor	ket Street		LE, DUNG ANH		
San Jose, CA 95113			ART UNIT	PAPER NUMBER	
			2818		
			DATE MAILED: 05/21/2003	DATE MAILED: 05/21/2003	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	plicant(s)
Office Action Summan	10/053,256	WANG ET AL.
Office Action Summary	Examiner	Art Unit
The MAILING DATE - Atti-	DUNG A LE	2818
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period w Failure to reply within the set or extended period for reply will, by statute, - Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b). Status	within the statutory minimum of thirty (30) days	ely filed will be considered timely. the mailing date of this communication.
1)⊠ Responsive to communication(s) filed on <u>01/1</u>	4/2003 .	
	s action is non-final.	
3) Since this application is in condition for alloward closed in accordance with the practice under EDisposition of Claims	nce except for formal matters income	osecution as to the merits is 53 O.G. 213.
4) Claim(s) 1-7 is/are pending in the application.		
4a) Of the above claim(s) is/are withdraw	n from consideration	
5) Claim(s) is/are allowed.	and the second s	
6) Claim(s) <u>1-7</u> is/are rejected.		
7) Claim(s) is/are objected to.		
8) Claim(s) are subject to restriction and/or	election requirement.	
Application Papers	,	
9) The specification is objected to by the Examiner.		
10) The drawing(s) filed on 8/27/2002 is/are: a) acc		
Applicant may not request that any objection to the	drawing(s) be held in abeyance. See	e 37 CFR 1.85(a).
11)☐ The proposed drawing correction filed on i		ed by the Examiner.
If approved, corrected drawings are required in reply		
12) The oath or declaration is objected to by the Exar	niner.	
Priority under 35 U.S.C. §§ 119 and 120		
13) Acknowledgment is made of a claim for foreign p	priority under 35 U.S.C. § 119(a)-	(d) or (f).
a) ☐ All b) ☐ Some * c) ☐ None of:		
1. Certified copies of the priority documents i		
2. Certified copies of the priority documents i		
3. Copies of the certified copies of the priority application from the International Burea * See the attached detailed Office action for a list of	au (PCT Rule 17.2(a)).	
14) ☐ Acknowledgment is made of a claim for domestic p		
a) ☐ The translation of the foreign language provis	sional application has been receiv	ved.
Attachment(s)	,	
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of Informal Pat	TO-413) Paper No(s) ent Application (PTO-152)
S Patent and Trademark Office PTO-326 (Rev. 04-01) Office Action	n Summary	Part of Paner No. 10

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DETAILED ACTION

Previous Office Action has been withdrawn, this is new ground of rejection.

Claim Objections

Claim objected to because of the following informalities:

ln claims 1 and 5, "wherein the edge of the first source mask does not coincide with a (SGE) attacked gate edge adjacent the shared source regions." should include in step b). Correction is required.

Claim Rejections

Claim Rejections - 35 USC § 112

Claims 1 and 5 are rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

In claim 1, the language of "the edge of the first source mask" and "the shared source regions" are insufficient antecedent basis in the claim.

In claim 5, the language of "the edge of the <u>first</u> source mask" and "the shared source regions" are insufficient antecedent basis in the claim.

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The remaining claims are dependent from the above rejected claims and therefore also considered indefinite.

Claim Rejections

Set of claims: 1-4

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-4 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lim (6265265) in view of The Background of the Invention.

Lim disclose a method of manufacturing a flash memory Electrically-Erasable Programmable Read-Only Memory (EEPROM) device having a lightly-doped source region near the critical gate region and a heavily-doped source region away from the critical gate region wherein the lateral diffusion of source dopants is decreased and having low Vss resistance, and wherein the EEPROM includes a multitude of field effect Application/Control Number: 10/053,256

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transistor memory cells each having a source, a drain, a floating gate 15, a control gate 17 and a substrate 11, the method comprising:

- (a) forming multiple gates on a substrate defining drain regions 29 and source regions 23 associated with each of the multiple gates (Fig. 2C);
- (b) forming a first source mask 21 exposing the source regions and portions of the gates (fig. 2C, col 2, line 53);
- (c) implanting the exposed source regions 23 with n dopant ions (lightly-doped region 23 as cited in reference column 3, line 5);
 - (d) removing the first source mask 21 (fig. 2D);
- (e) forming a second source mask 25 exposing a portion of the source regions (fig. 2D, col 3, lines 1-2);
- (f) implanting the exposed portions of the source regions with n+ dopant ions (implanting a large amount of an N type impurity, see column 3, line 2-5).

wherein the edge of the first source mask 21 does not coincide with a (SGE) attacked gate edge adjacent the shared source regions 23/27

Lim does not disclose the step (g) removing the second source mask after implanting the exposed portions of the source regions with n+ dopant ions.

However, The Background of the Invention shows the step of removing the second source mask 128 after implanting the exposed portions of the source regions with n+ dopant ions as set forth in figure 1D and page 6, lines 16- 18.

Accordingly, it would have been obvious to one of ordinary skill in the art at the time the invention was made to remove the second source mask after implanting the exposed portions of the source regions with n+ dopant ions, as taught by The Background of the Invention in order to complete the fabricating method of making the flash memory cell by implanting large amount of an N-type impurity into the exposed portion of semiconductor substrate, wherein the source region is position over the lightly doped region in cross-sectional style.

Regarding claim 2, The Background of the Invention teach an annealing the device (page 6, line 17).

Regarding claim 3, Lim shows the step (c) is accomplished by implanting n dopant ions at a low dosage and at low energy in column 2, line 55 (as cited in Lim's reference, since a lightly doped region is formed by implanting and N type impurity into the exposed portion, it is inherent that the step implanting the exposed source regions with N dopant ions is performed at a low dosage and at low energy).

Regarding claim 4, Lim also shows step (f) is accomplished by implanting n dopant ions a high dosage and at high energy in column 3, lines 2-3. (as cited in Lim's reference, since source region 27 is formed by an implanting large amount of an N-type

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impurity, wherein the source region 27 is positioned over the lightly-doped-region 23, it is inherent that the step implanting the exposed source regions with N dopant ions is performed at a high dosage and at high energy.)

Set of claims: 5-7.

Claims 5-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lim (6265265) in view of The Background of the Invention.

Lim disclose a method of manufacturing a flash memory Electrically-Erasable

Programmable Read-Only Memory (EEPROM) device having a lightly-doped source
region near the critical gate region and a heavily-doped source region away from the
critical gate region wherein the lateral diffusion of source dopants is decreased and
having low Vss resistance, and wherein the EEPROM includes a multitude of field effect
transistor memory cells each having a source, a drain, a floating gate 17, a control gate

15 and a substrate 11, the method comprising:

- (a) forming multiple gates on a substrate defining drain regions and source regions associated with each of the multiple gates (fig. 2C);
- (b) forming a source mask 21 exposing portions of the source regions 23 (fig. 2D, col 3, line 1-2);
- (c) implanting the exposed portions of the source regions 27 with n+ dopant ions (fig. 2D, col 3, lines 2-5).

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wherein the edge of the first source mask 21 does not coincide with a (SGE) attacked gate edge adjacent the shared source regions 23/27

Lim does not disclose the step (d) removing the source mask.

However, The Background of the Invention teaches the step (d) removing the source mask 128 (figure 1D, page 6, lines 16-18).

Accordingly, it would have been obvious to one of ordinary skill in the art at the time the invention was made to remove the source mask, as taught by The Background of the Invention in order to complete the fabricating method of making the flash memory cell by implanting large amount of an N-type impurity into the exposed portion of semiconductor substrate as source regions.

Regarding claim 6, The Background of the Invention teach an annealing the device (page 6, line 17).

Regarding claim 7, Lim also shows step (c) is accomplished by implanting n dopant ions a high dosage and at high energy in column 3, lines 2-3. (as cited in Lim's reference, since source region 27 is formed by an implanting large amount of an N-type impurity, wherein the source region 27 is positioned over the lightly-doped-region 23, it is inherent that the step implanting the exposed source regions with N dopant ions is performed at a high dosage and at high energy).

When responding to the office action, Applicants' are advice to provide the examiner with the line numbers and page numbers in the application and/or references cited to assist the examiner to locate the appropriate paragraphs.

A shortened statutory period for response to this action is set to expire 3 (three) months and 0 (zero) day from the day of this letter. Failure to respond within the period for response will cause the application to become abandoned (see M.P.E.P 710.02(b)).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dung A. Le whose telephone number is 703-306-5797. The examiner can normally be reached on Monday-Friday 8:00am-5: 30pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David Nelms can be reached on 703-308-4910. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

Dung A. Le)/(Examiner

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